

High-Voltage Types (20-Volt Rating)

CD4045B Types

STATIC ELECTRICAL CHARACTERISTICS

CHARACTERISTIC	CONDITIONS			LIMITS AT INDICATED TEMPERATURES (°C)							UNITS
	V _O (V)	V _{IN} (V)	V _{DD} (V)	-55	-40	+85	+125	+25			
								Min.	Typ.	Max.	
Quiescent Device Current, I _{DD} Max.	—	0,5	5	5	5	150	150	—	0.04	5	μA
	—	0,10	10	10	10	300	300	—	0.04	10	
	—	0,15	15	20	20	600	600	—	0.04	20	
	—	0,20	20	100	100	3000	3000	—	0.08	100	
Output Low (Sink) Current I _{OL} Min.	0.4	0,5	5	4.5	4.3	2.9	2.5	3.6	7	—	mA
	0.5	0,10	10	11.2	10.5	7.7	6.3	9.1	18	—	
	1.5	0,15	15	29.4	28	19.6	16.8	23.8	47	—	
Output High (Source) Current, I _{OH} Min.	4.6	0,5	5	-4.5	-4.3	-2.9	-2.5	-3.6	-7	—	mA
	9.5	0,10	10	-11.2	-10.5	-7.7	-6.3	-9.1	-18	—	
	13.5	0,15	15	-29.4	-28	-19.6	-16.8	-23.8	-47	—	
Pin 15 Output Low and High Current, I _{OL} , I _{OH}	0.4,4.6	0,5	5	—				±0.1	±0.18	—	mA
	0.5,9.5	0,10	10	—				±0.2	±0.3	—	
	1.5,13.5	0,15	15	—				±0.5	±1	—	
Output Voltage: Low-Level, V _{OL} Max.	—	0,5	5	0.05				—	—	0.05	V
	—	0,10	10	0.05				—	—	0.05	
	—	0,15	15	0.05				—	—	0.05	
Output Voltage: High-Level, V _{OH} Min.	—	0,5	5	4.95				4.95	5	—	V
	—	0,10	10	9.95				9.95	10	—	
	—	0,15	15	14.95				14.95	15	—	
Input Low Voltage V _{IL} Max.	0.5,4.5	—	5	1.5				—	—	1.5	V
	1,9	—	10	3				—	—	3	
	1.5,13.5	—	15	4				—	—	4	
Input High Voltage, V _{IH} Min.	0.5,4.5	—	5	3.5				3.5	—	—	V
	1,9	—	10	7				7	—	—	
	1.5,13.5	—	15	11				11	—	—	
Input Current I _{IN} Max.	—	0,18	18	±0.1	±0.1	±1	±1	—	±10 ⁻⁵	±0.1	μA

RECOMMENDED OPERATING CONDITIONS

For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges

CHARACTERISTIC	V _{DD} (V)	LIMITS		UNITS
		Min.	Max.	
Supply-Voltage Range (For T _A = Full Package-Temperature Range)	—	3	18	V
Minimum Input-Pulse Width, t _W	5	—	100	ns
	10	—	50	
	15	—	40	
Maximum Input-Pulse Frequency, f _φ (External Pulse Source)	5	5	—	MHz
	10	12	—	
	15	15	—	

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DYNAMIC ELECTRICAL CHARACTERISTICS at $T_A = 25^\circ\text{C}$; Input $t_r, t_f = 20\text{ ns}$,
 $C_L = 50\text{ pF}$, $R_L = 200\text{ k}\Omega$

CHARACTERISTIC	TEST CONDITIONS	V_{DD} V	LIMITS			UNITS
			Min.	Typ.	Max.	
Propagation Delay Time: ϕ_1 to y or y+d out t_{PHL}, t_{PLH}		5 10 15	— — —	2.2 0.9 0.65	5.5 2.7 2	μs
Transition Time: t_{THL}, t_{TLH}		5 10 15	— — —	25 13 10	50 25 20	ns
Minimum Input-Pulse Width t_W		5 10 15	— — —	50 25 20	100 50 40	ns
Input-Pulse Rise or Fall Time: $t_r\phi, t_f\phi$		5 10 15	— — —	— — —	500 500 500	μs
Maximum Input-Pulse Frequency: (External Pulse Source) f_ϕ		5 10 15	5 12 15	10 25 30	— — —	MHz
Input Capacitance, C_{IN}	Any Input		—	5	7.5	pF
Variation of Output Frequency (Unit-to-Unit)	$f = 5\text{ MHz}$	5 10 15	— — —	0.05 0.03 0.1	— — —	%
RC Oscillator Operation						
Maximum Oscillator Frequency (See Fig. 11) f_{osc}	$R_X = 50\text{ k}\Omega$, $R_S = 560\text{ k}\Omega$, $C_X = 50\text{ pF}$	5 10 15	45 45 45	60 60 60	75 75 75	kHz

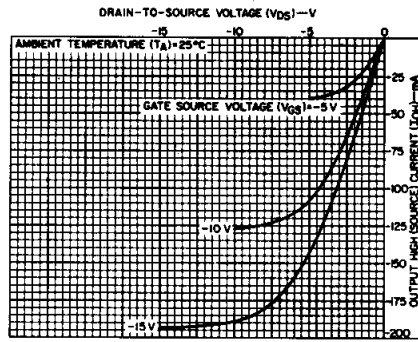


Fig. 4 - Typical output high (source) current characteristics.

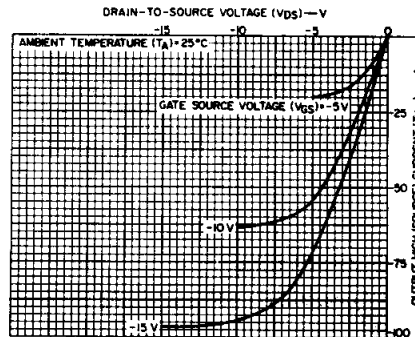


Fig. 5 - Minimum output high (source) current characteristics.

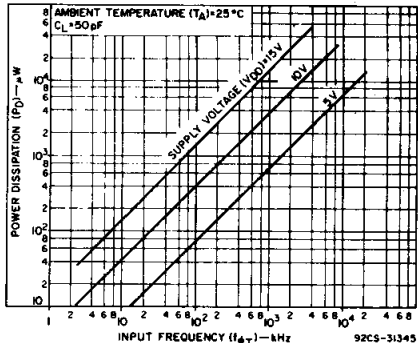


Fig. 7 - Typical power dissipation as a function of input frequency (21 counting stages).

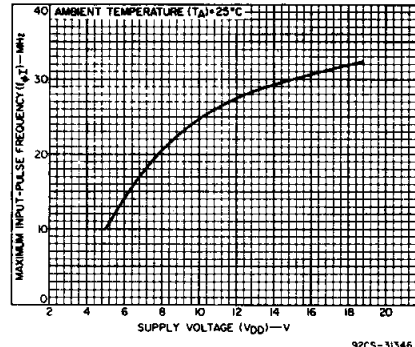


Fig. 8 - Typical maximum input-pulse frequency as a function of supply voltage.

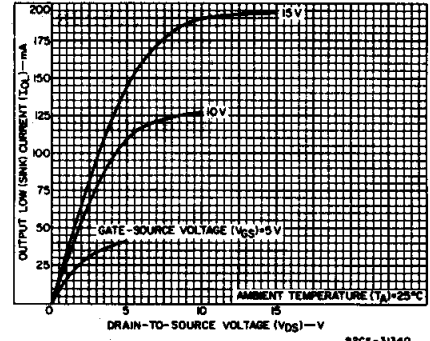


Fig. 2 - Typical output low (sink) current characteristics.

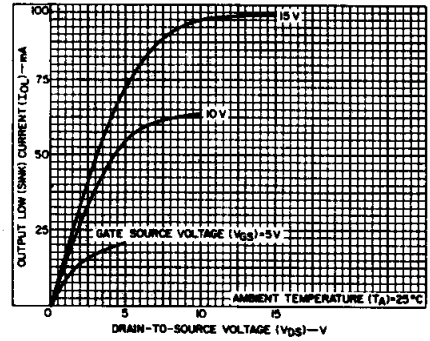


Fig. 3 - Minimum output low (sink) current characteristics.

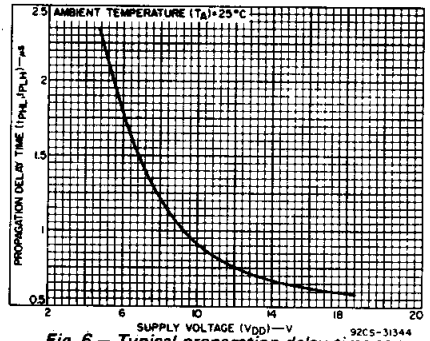


Fig. 6 - Typical propagation delay time as a function of supply voltage (ϕ_1 to y or y + d out vs. V_{DD}).

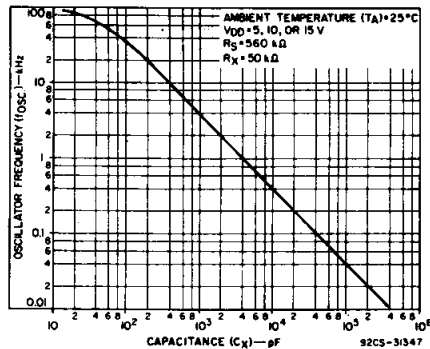


Fig. 9 - Typical RC oscillator frequency as a function of capacitance (C_X), See Fig. 11.

CD4045B Types

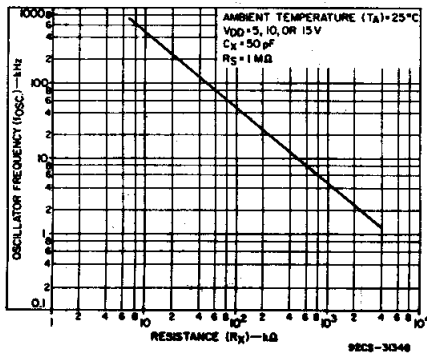


Fig. 10 - Typical RC oscillator frequency as a function of resistance (R_X). See Fig. 11.

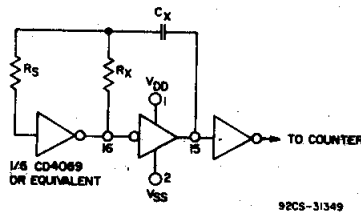


Fig. 11 - Typical RC circuit.

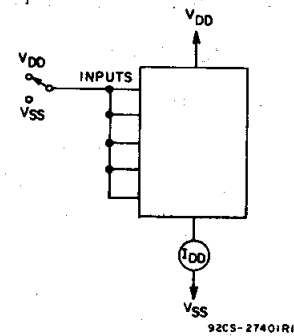


Fig. 12 - Quiescent-device-current test circuit.

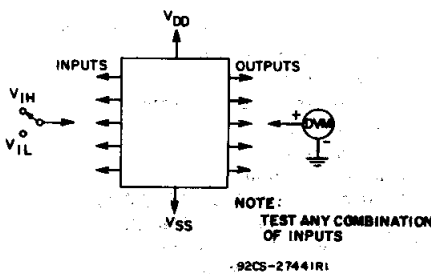


Fig. 13 - Noise-immunity test circuit.

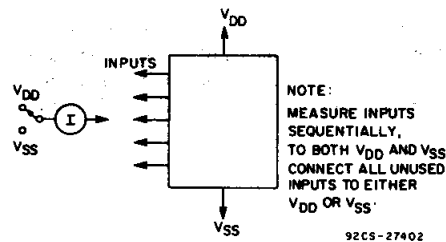


Fig. 14 - Input-leakage-current test circuit.

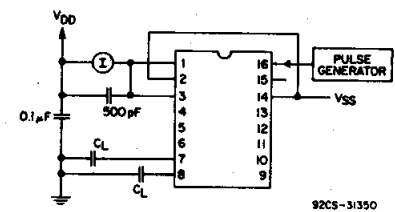
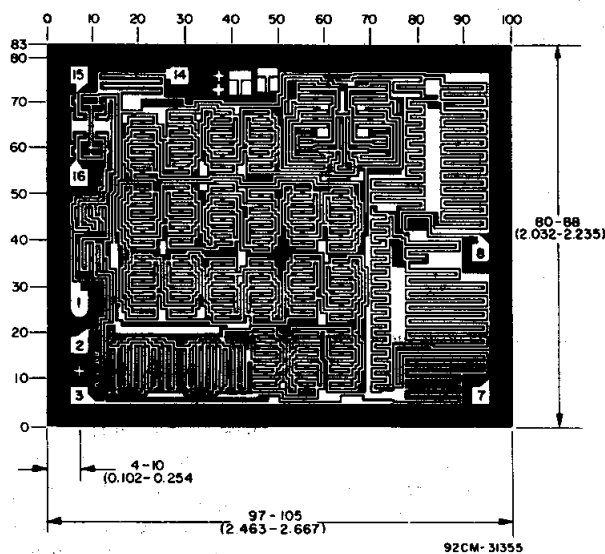


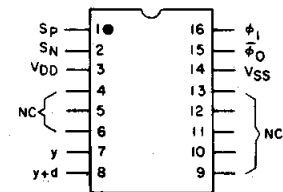
Fig. 15 - Dynamic power dissipation test circuit.



Chip dimensions and pad layout for CD4045B

Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils (10^{-3} inch).

TERMINAL DIAGRAM Top View



NC = NO CONNECTION

NOTE Observe power-supply terminal connections, V_{DD} is terminal No. 3 and V_{SS} is terminal No. 14 (not 16 and 8 respectively, as in other CD4000B Series 16-lead devices).

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
CD4045BE	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD4045BEE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CD4045BPWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4045BPWRE4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CD4045BPWRG4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD4045BPWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



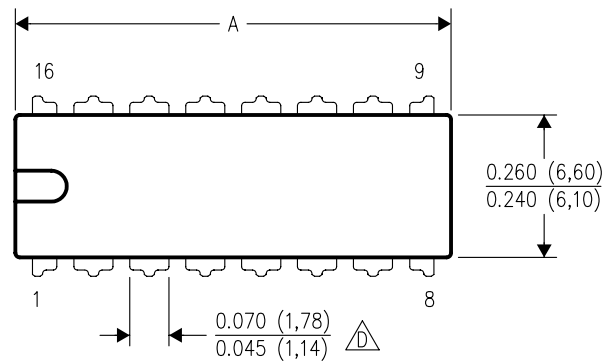
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD4045BPWR	TSSOP	PW	16	2000	367.0	367.0	35.0

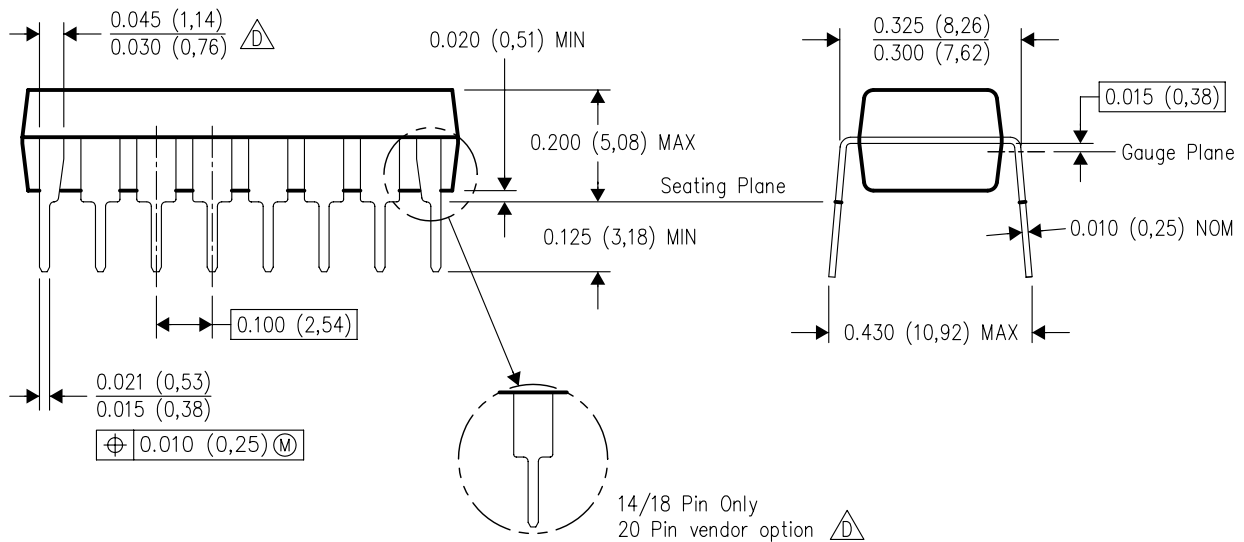
N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



4040049/E 12/2002

NOTES:

- A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
-  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 The 20 pin end lead shoulder width is a vendor option, either half or full width.

PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE

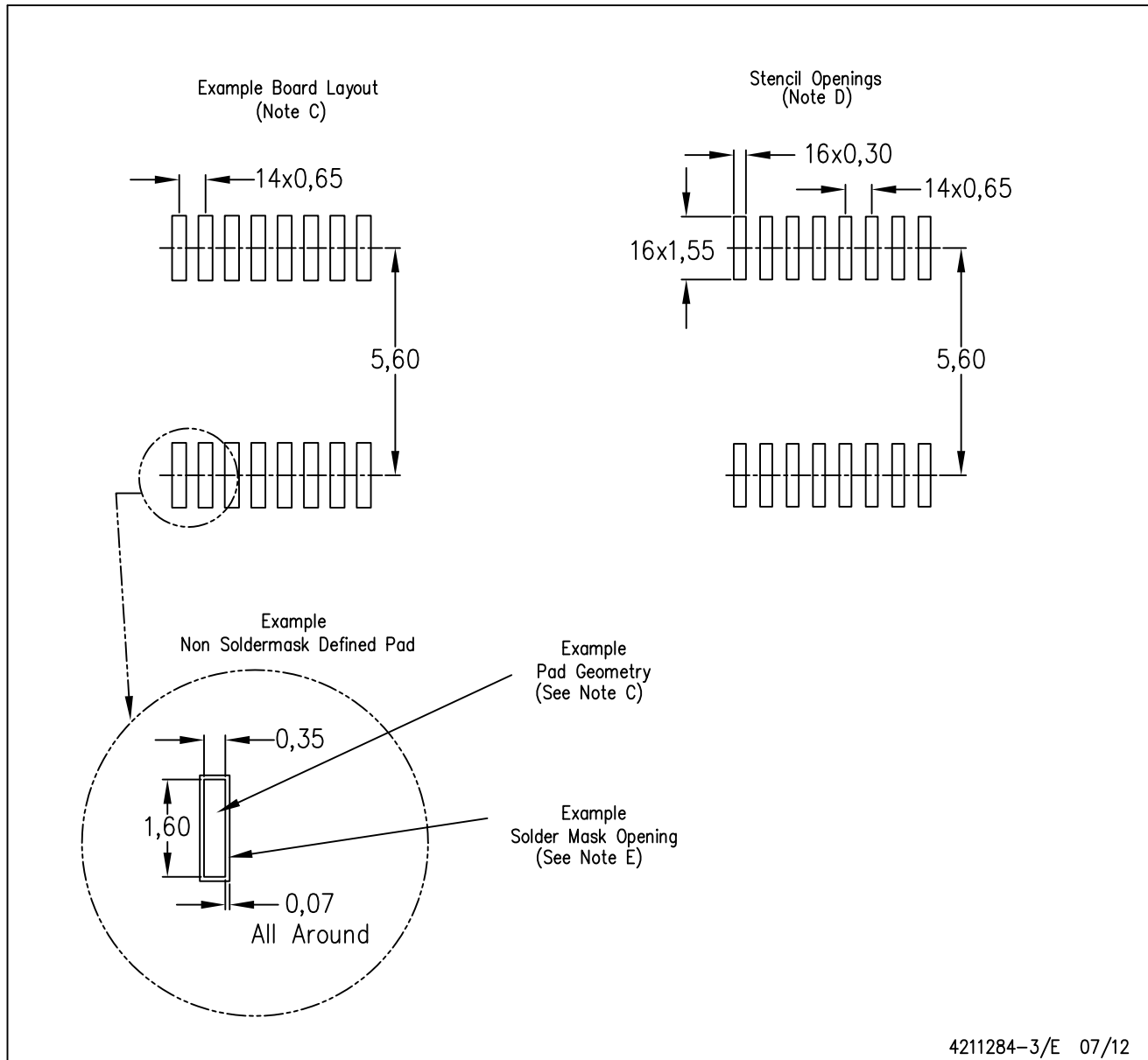


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- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
 - E. Falls within JEDEC MO-153

PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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